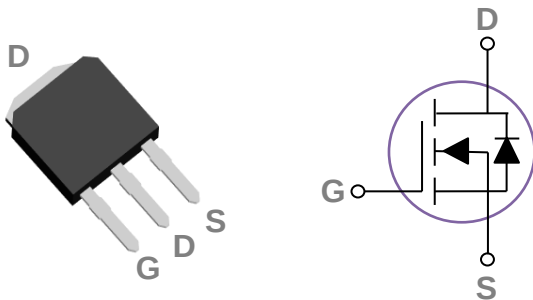


General Description

These N-Channel enhancement mode power field effect transistors are using Super Junction technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply

TO251 Pin Configuration



BVDSS	RDS(on)	ID
600V	960mΩ	4A

Features

- 600V, 4A, $R_{DS(ON)} = 960m\Omega$ @ $V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- High efficient switched mode power supplies
- LED Lighting
- Adapter/charger

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	600	V
V_{GS}	Gate-Source Voltage	± 30	V
I_D	Drain Current – Continuous (Tc=25°C)	4	A
	Drain Current – Continuous (Tc=100°C)	2.5	A
I_{DM}	Drain Current – Pulsed ¹	16	A
EAS	Single Pulse Avalanche Energy ²	129	mJ
P_D	Power Dissipation (Tc=25°C)	29	W
	Power Dissipation – Derate above 25°C	0.23	W/°C
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62.5	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	4.3	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	600	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =600V, V _{GS} =0V, T _J =25°C	---	---	1	μA
		V _{DS} =480V, V _{GS} =0V, T _J =125°C	---	---	10	μA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±30V, V _{DS} =0V	---	---	±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =2A	---	800	960	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250μA	2.5	3	3.5	V

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{2, 3}	V _{DS} =480V, V _{GS} =10V, I _D =2A	---	8.2	---	nC
Q _{gs}	Gate-Source Charge ^{2, 3}		---	0.7	---	
Q _{gd}	Gate-Drain Charge ^{2, 3}		---	3.7	---	
T _{d(on)}	Turn-On Delay Time ^{2, 3}	V _{DD} =480V, V _{GS} =10V, R _G =25Ω I _D =2A	---	6	---	ns
T _r	Rise Time ^{2, 3}		---	12	---	
T _{d(off)}	Turn-Off Delay Time ^{2, 3}		---	14	---	
T _f	Fall Time ^{2, 3}		---	22	---	
C _{iss}	Input Capacitance	V _{DS} =100V, V _{GS} =0V, F=1MHz	---	245	---	pF
C _{oss}	Output Capacitance		---	17	---	
C _{rss}	Reverse Transfer Capacitance		---	3.5	---	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	---	4	---	Ω

Guaranteed Avalanche Energy

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	V _{DD} =100V, L=79.9mH, I _{AS} =1A	40	---	---	mJ

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	4	A
I _{SM}	Pulsed Source Current		---	---	8	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =2A, T _J =25°C	---	---	1.4	V
t _{rr}	Reverse Recovery Time	I _S =2A	---	140	---	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs, T _J =25°C	---	760	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300μs , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

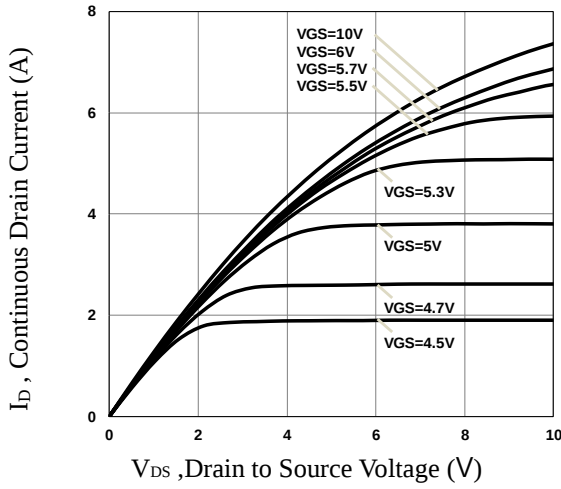


Fig.1 Typical Output Characteristics

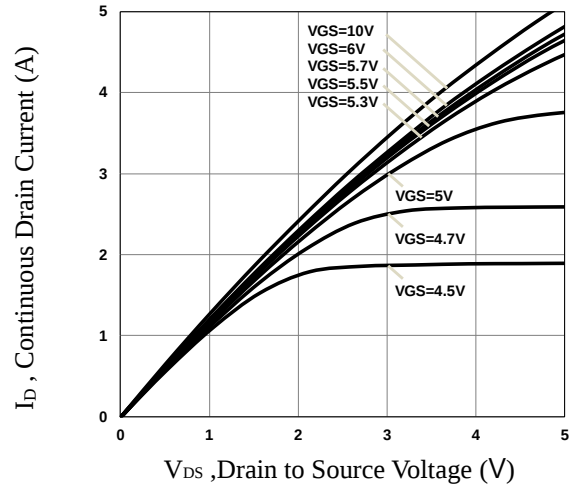


Fig.2 Typical Output Characteristics

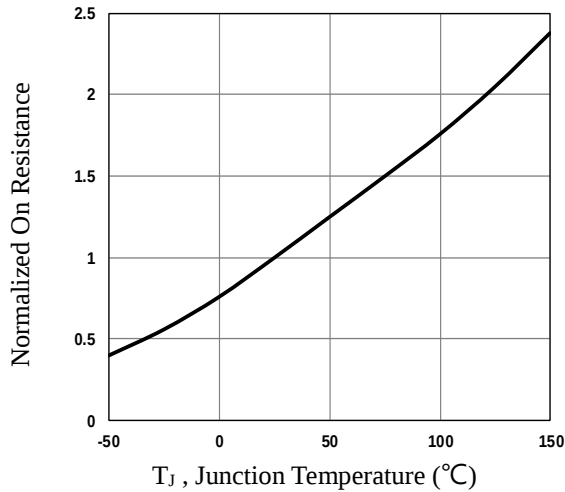


Fig.3 Normalized $R_{DS(on)}$ vs. T_J

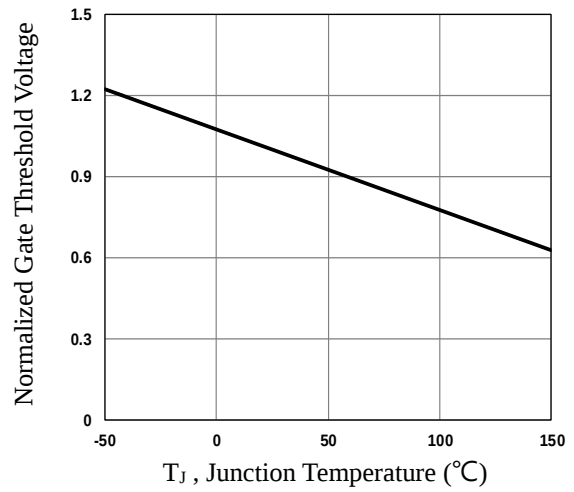


Fig.4 Normalized V_{th} vs. T_J

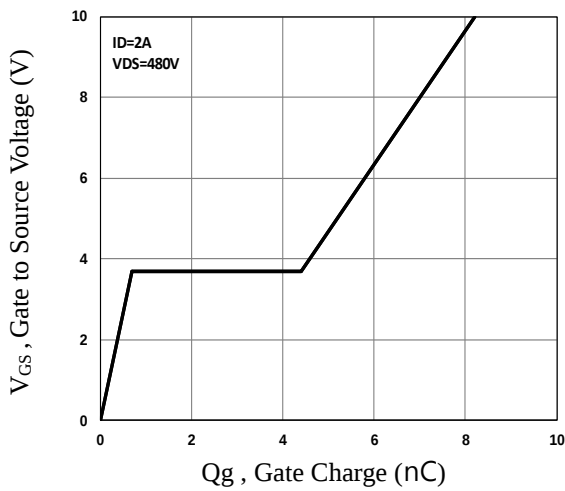


Fig.5 Gate Charge Characteristics

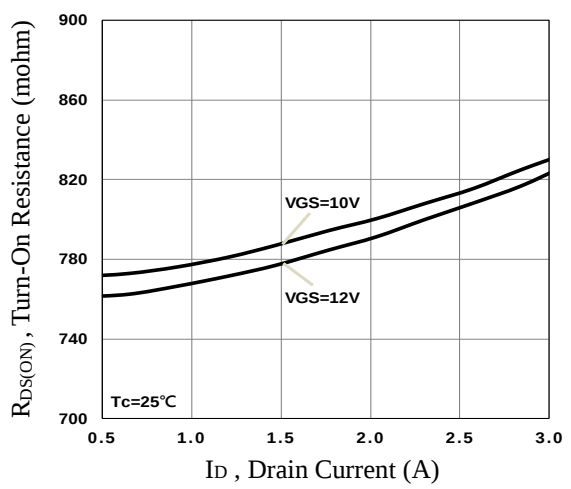


Fig.6 Turn-On Resistance vs. I_D

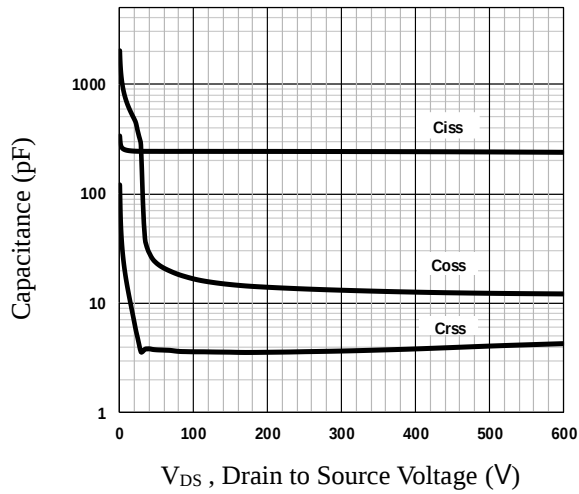


Fig.7 Capacitance Characteristics

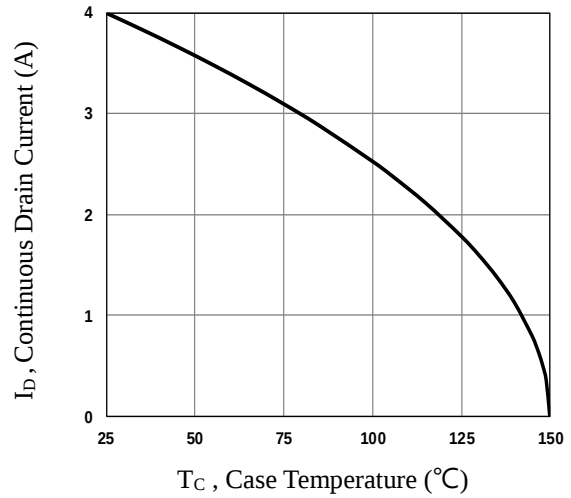


Fig.8 Continuous Drain Current vs. T_c

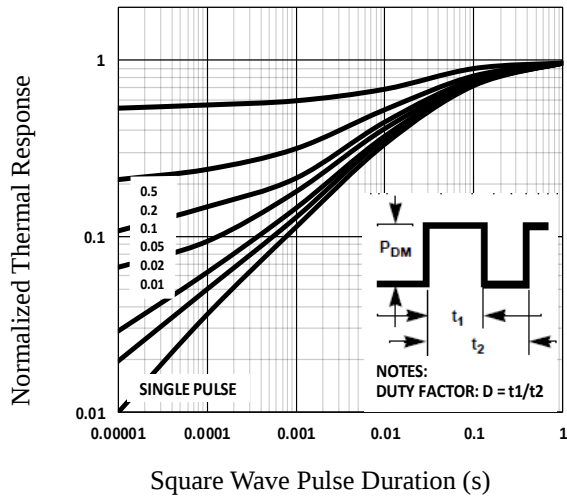


Fig.9 Normalized Transient Impedance

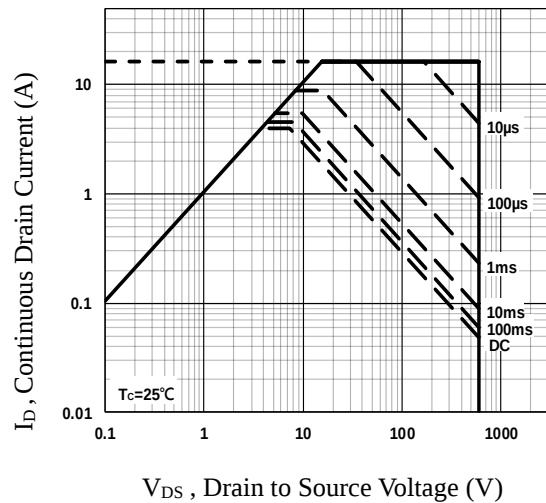


Fig.10 Maximum Safe Operation Area

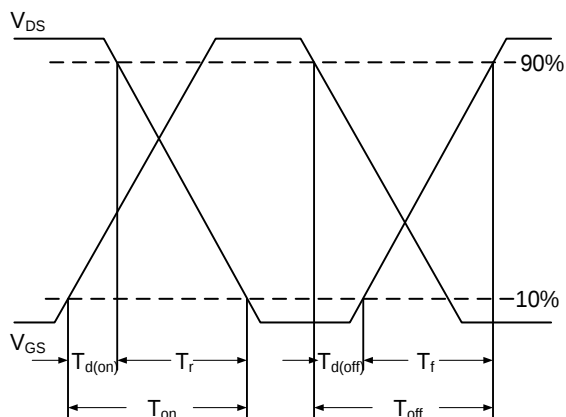


Fig.11 Switching Time Waveform

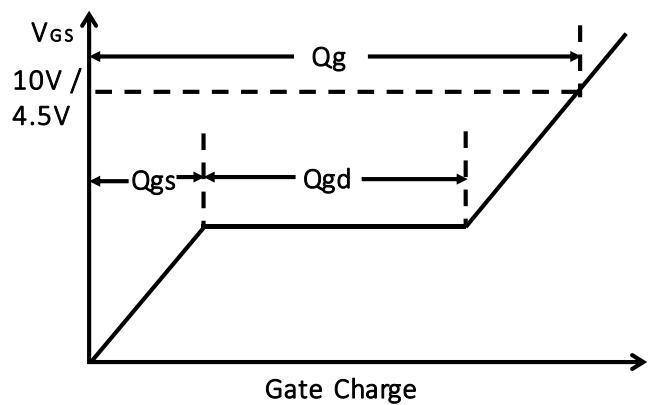
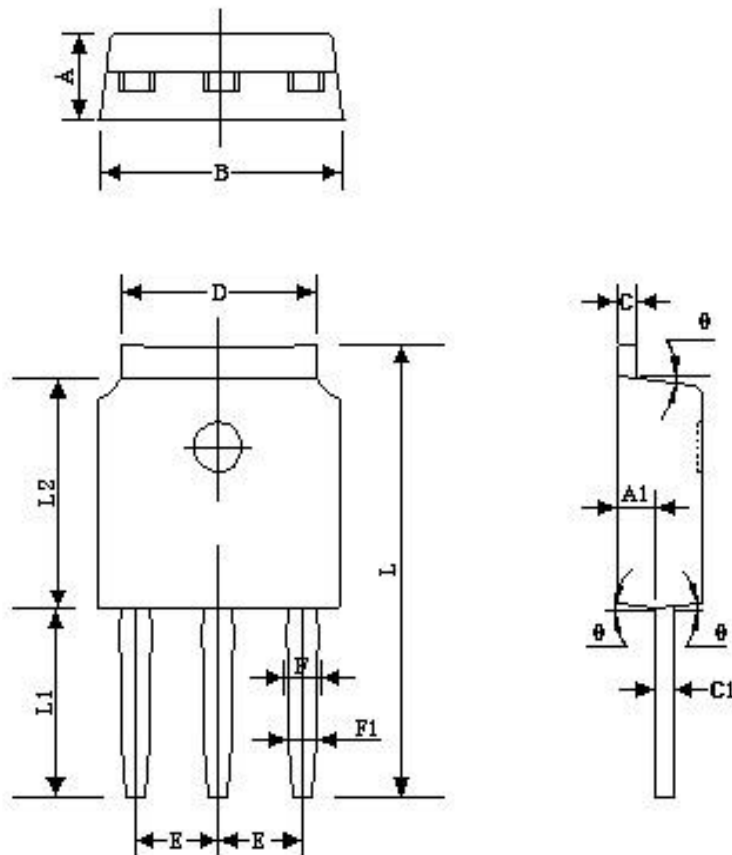


Fig.12 Gate Charge Waveform

TO251 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.500	2.100	0.098	0.083
A1	1.250	0.900	0.049	0.035
B	6.800	6.400	0.268	0.252
C	0.580	0.420	0.023	0.017
C1	0.580	0.420	0.023	0.017
D	5.500	5.000	0.217	0.197
E	2.400	2.000	0.094	0.079
F	1.050	0.750	0.041	0.030
F1	0.900	0.650	0.035	0.026
L	12.400	11.600	0.488	0.457
L1	5.300	4.700	0.209	0.185
L2	6.300	5.700	0.248	0.224
θ	9°	3°	9°	3°